

Date: Thursday, April 17, 2008

Subject: Process and Considerations: Replacement of BGA's
with Reclaimed Devices

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#	Suggested Technical Topics:	
1	Selection of Electronic Contract Assembly House for Aerospace	1
2	Impact on component reliability after multiple reflows	1
3	Does the device characteristics change memory device	1
4	Conformal coating for assemblies operation at 40GHZ	1
5	BGA's Attachment	1
6	Organization of CM-different departments and their responsibility - what key departments are needed.	1
7	Underfill	2
8	SN100 vs SAC305 Tin Wiskers comparison	1
9	Solder paste inspection	1
10	Failure analysis on solder joints/micro cracks	1
11	ESD controls	1
12	Closed-loop process feedback	1
13	BGA rework	1
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